Solder plus Support

J8 NO CLEAN JETTING SOLDER PASTE

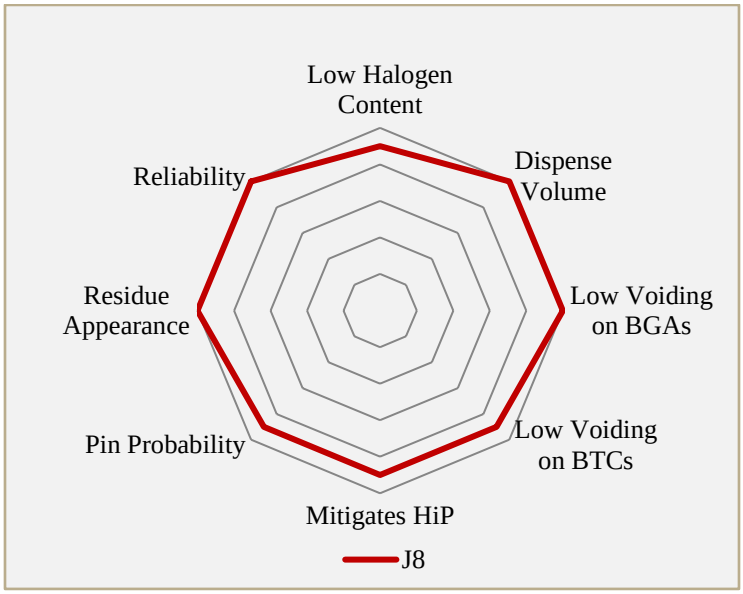
FEATURES

- Capable of 200µm deposits
- Low Voiding: <5% on BGA and <10% on BTC Components
- Eliminates HiP Defects
- REACH and RoHS* Compliant
- Powerful Wetting on Lead-Free Surface Finishes
- Passes Bono Testing
- Available in SAC305 and Sn63 Alloys

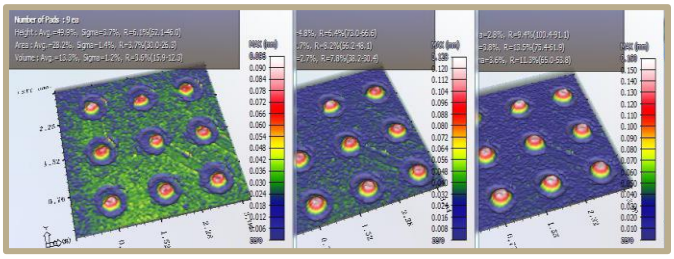
DESCRIPTION

AIM's J8 No Clean Jetting Solder Paste is specially formulated for use with jetting equipment providing consistent solder deposits as small as 200µm. J8 is fully compatible with all AIM no clean solder pastes for use in applications where combining jetted paste deposits with printed paste deposits is required. J8 has a novel activator system providing powerful, durable wetting action accommodating a wide range of profiling producing bright shiny joints without graping defects. J8 has reduced voiding to as low as <5% on BGA and <10% on BTC ground pads.

CHARACTERISTICS



*Lead-free alloys



HANDLING & STORAGE

Parameter	Time	Temperature
Sealed Refrigerated Shelf Life	6 Months	0°C-12°C (32°F-54°F)
Sealed Unrefrigerated Shelf Life	2 Days	< 25°C (< 77°F)

J8 is supplied in EFD Optimum 5cc Syringe Barrels. Barrels should be stored refrigerated, tip down and removed from refrigeration 4-6 hours prior to use. J8 should not be returned to refrigeration. After opening, solder paste shelf life is environment and application dependent. See AIM's paste handling guidelines for further information. Alloy and storage conditions may affect shelf life. Please refer to J8 Certificate of Analysis for product specific information.

CLEANING

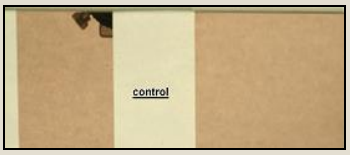
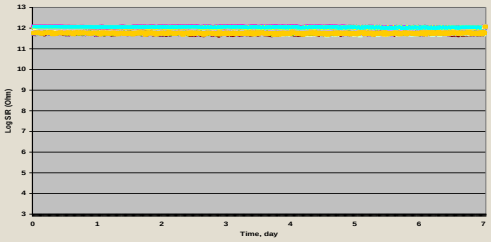
Pump assembly should be cleaned per manufacturer's instructions.

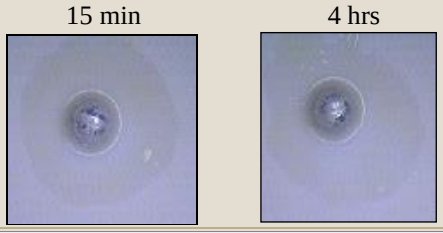
Post-Reflow Flux Residue: J8 residues can remain on the assembly after reflow and do not require cleaning. Where cleaning is mandated, AIM has worked closely with industry partners to ensure that J8 residues can be effectively removed with common defluxing agents. Contact AIM for cleaning compatibility information.

REFLOW PROFILE

Detailed profile information may be found at http://www.aimsolder.com/reflow-profile-supplements. Contact AIM for additional information.

TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ROL0	
IPC Flux Classification	J-STD-004B 3.3.1	ROL1	
Name	**Test Method**	**Typical Results**	**Image**
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	Before  After 
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	Br: 0.24% Cl: 0.0% Typical	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No fluoride	
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	All measurements on test patterns exceed 100 MΩ	

Name	Test Method	Typical Results	Image
Bono Testing		PASS Fc<8.0 Typical	
Oxygen Bomb Halogen Testing	EN14582:2007 SW 9056 SW 5050	Br 265 mg/Kg Cl <122 mg/Kg	
Electrochemical Migration	J-STD-004B 3.4.1.5 IPC-TM-650 2.6.14.1	PASS	
Flux Solids, Nonvolatile Determination	J-STD-004B 3.4.2.1 IPC-TM-650 2.3.34	94.77% Typical	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	135.95 mgKOH/g flux Typical	
Viscosity	J-STD-004B 3.4.2.4 IPC-TM-650 2.4.34	200-500 Kcps	
Visual	J-STD-004B 3.4.2.5	PASS	
Slump	J-STD-005A 3.6 IPC-TM-650 2.4.35	PASS	
Solder Ball	J-STD-005A 3.7 IPC-TM-650 2.4.43	PASS	
Tack	J-STD-005A 3.8 IPC-TM-650 2.4.44	36.1 gf Time 0 Typical